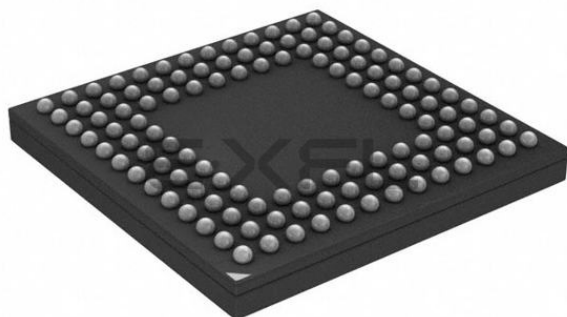




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	120-VFBGA
Supplier Device Package	120-BGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg895f128g-e-bga120

3.2.8 EFM32LG360	.25
3.2.9 EFM32LG380	.27
3.2.10 EFM32LG390	.29
3.2.11 EFM32LG395	.31
3.2.12 EFM32LG840	.33
3.2.13 EFM32LG842	.35
3.2.14 EFM32LG880	.37
3.2.15 EFM32LG890	.39
3.2.16 EFM32LG895	.41
3.2.17 EFM32LG900	.43
3.2.18 EFM32LG940	.45
3.2.19 EFM32LG942	.47
3.2.20 EFM32LG980	.49
3.2.21 EFM32LG990	.51
3.2.22 EFM32LG995	.53
3.3 Memory Map	.55
4. Electrical Characteristics	57
4.1 Test Conditions	.57
4.1.1 Typical Values	.57
4.1.2 Minimum and Maximum Values	.57
4.2 Absolute Maximum Ratings	.57
4.3 General Operating Conditions	.57
4.4 Current Consumption	.58
4.4.1 EM1 Current Consumption	.60
4.4.2 EM2 Current Consumption	.63
4.4.3 EM3 Current Consumption	.64
4.4.4 EM4 Current Consumption	.64
4.5 Transition between Energy Modes	.65
4.6 Power Management	.65
4.7 Flash	.66
4.8 General Purpose Input Output	.67
4.9 Oscillators	.75
4.9.1 LFXO	.75
4.9.2 HFXO	.75
4.9.3 LFRCO	.76
4.9.4 HFRCO	.77
4.9.5 AUXHFRCO	.82
4.9.6 ULFRCO	.82
4.10 Analog Digital Converter (ADC)	.83
4.10.1 Typical Performance	.89
4.11 Digital Analog Converter (DAC)	.94
4.12 Operational Amplifier (OPAMP)	.96
4.13 Analog Comparator (ACMP)	103

Module	Configuration	Pin Connections
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	90 pins	Available pins are shown in 5.4.3 GPIO Pinout Overview

Module	Configuration	Pin Connections
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	86 pins	Available pins are shown in 5.10.3 GPIO Pinout Overview

Module	Configuration	Pin Connections
AES	Full configuration	NA
GPIO	56 pins	Available pins are shown in 5.12.3 GPIO Pinout Overview
LCD	Full configuration	LCD_SEG[19:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

Module	Configuration	Pin Connections
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	50 pins	Available pins are shown in 5.19.3 GPIO Pinout Overview
LCD	Full configuration	LCD_SEG[15:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

4.5 Transition between Energy Modes

The transition times are measured from the trigger to the first clock edge in the CPU.

Table 4.4. Energy Modes Transitions

Parameter	Symbol	Min	Typ	Max	Unit
Transition time from EM1 to EM0	t_{EM10}	—	0	—	HFCORECLK cycles
Transition time from EM2 to EM0	t_{EM20}	—	2	—	μs
Transition time from EM3 to EM0	t_{EM30}	—	2	—	μs
Transition time from EM4 to EM0	t_{EM40}	—	163	—	μs

4.6 Power Management

The EFM32LG requires the AVDD_x, VDD_DREG and IOVDD_x pins to be connected together (with optional filter) at the PCB level. For practical schematic recommendations, please see the application note, *AN0002 EFM32 Hardware Design Considerations*.

Table 4.5. Power Management

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
BOD threshold on falling external supply voltage	$V_{BODextthr-}$		1.74	—	1.96	V
BOD threshold on rising external supply voltage	$V_{BODextthr+}$		—	1.85	1.98	V
Power-on Reset (POR) threshold on rising external supply voltage	$V_{PORthr+}$		—	—	1.98	V
Delay from reset is released until program execution starts	t_{RESET}	Applies to Power-on Reset, Brown-out Reset and pin reset.	—	163	—	μs
Voltage regulator decoupling capacitor.	$C_{DECOUPLE}$	X5R capacitor recommended. Apply between DECOUPLE pin and GROUND	—	1	—	μF
USB voltage regulator out decoupling capacitor.	C_{USB_VREGO}	X5R capacitor recommended. Apply between USB_VREGO pin and GROUND	—	1	—	μF
USB voltage regulator in decoupling capacitor.	C_{USB_VREGI}	X5R capacitor recommended. Apply between USB_VREGI pin and GROUND	—	4.7	—	μF

4.10 Analog Digital Converter (ADC)

Table 4.14. ADC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{ADCIN}	Single ended	0	—	V_{REF}	V
		Differential	$-V_{\text{REF}}/2$	—	$V_{\text{REF}}/2$	V
Input range of external reference voltage, single ended and differential	V_{ADCREFIN}		1.25	—	V_{DD}	V
Input range of external negative reference voltage on channel 7	$V_{\text{ADCREFIN_CH7}}$	See V_{ADCREFIN}	0	—	$V_{\text{DD}} - 1.1$	V
Input range of external positive reference voltage on channel 6	$V_{\text{ADCREFIN_CH6}}$	See V_{ADCREFIN}	0.625	—	V_{DD}	V
Common mode input range	V_{ADCCMIN}		0	—	V_{DD}	V
Input current	I_{ADCIN}	2 pF sampling capacitors	—	<100	—	nA
Analog input common mode rejection ratio	CMRR_{ADC}		—	65	—	dB
Average active current	I_{ADC}	1 MSamples/s, 12 bit, external reference	—	351	—	μA
		10 kSamples/s 12 bit, internal 1.25 V reference, WARMUP-MODE in ADCn_CTRL set to 0b00	—	67	—	μA
		10 kSamples/s 12 bit, internal 1.25 V reference, WARMUP-MODE in ADCn_CTRL set to 0b01	—	63	—	μA
		10 kSamples/s 12 bit, internal 1.25 V reference, WARMUP-MODE in ADCn_CTRL set to 0b10	—	64	—	μA
Input capacitance	C_{ADCIN}		—	2	—	pF
Input ON resistance	R_{ADCIN}		1	—	—	M Ω
Input RC filter resistance	R_{ADCFILT}		—	10	—	k Ω
Input RC filter/decoupling capacitance	C_{ADCFILT}		—	250	—	fF
Input bias current	$I_{\text{ADCBIASIN}}$	$V_{\text{SS}} < V_{\text{IN}} < V_{\text{DD}}$	-40	—	40	nA
Input offset current	$I_{\text{ADCOFFSETIN}}$	$V_{\text{SS}} < V_{\text{IN}} < V_{\text{DD}}$	-40	—	40	nA
ADC Clock Frequency	f_{ADCCLK}		—	—	13	MHz
Conversion time	t_{ADCCONV}	6 bit	7	—	—	ADCCLK Cycles
		8 bit	11	—	—	ADCCLK Cycles
		12 bit	13	—	—	ADCCLK Cycles

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range(SFDR)	SFDR _{DAC}	500 kSamples/s, 12 bit, single ended, internal 1.25V reference	—	62	—	dBc
		500 kSamples/s, 12 bit, single ended, internal 2.5V reference	—	56	—	dBc
		500 kSamples/s, 12 bit, differential, internal 1.25V reference	—	61	—	dBc
		500 kSamples/s, 12 bit, differential, internal 2.5V reference	—	55	—	dBc
		500 kSamples/s, 12 bit, differential, V _{DD} reference	—	60	—	dBc
Offset voltage, all packages except CSP	V _{DACOFF-SET}	After calibration, single ended	—	2	9	mV
		After calibration, differential	—	2	—	mV
Offset voltage, CSP devices	V _{DACOFF-SET}	After calibration, single ended	—	2	—	mV
		After calibration, differential	—	2	—	mV
Differential non-linearity	DNL _{DAC}		—	±1	—	LSB
Integral non-linearity	INL _{DAC}		—	±5	—	LSB
No missing codes	MC _{DAC}		—	12	—	bits
VREF output voltage	V _{REF}	1.25 V reference	1.2	1.25	1.3	V
		2.5 V reference	2.4	2.5	2.6	V
VREF voltage drift	V _{REF_VDRIFT}	1.25 V reference	-12.4	2.3	18.2	mV/V
		2.5 V reference, VDD > 2.5 V	-24.6	5.3	35.2	mV/V
VREF temperature drift	V _{REF_TDRIFT}	1.25 V reference	-132	242	677	μV/°C
		2.5 V reference	-231	507	1271	μV/°C
VREF current consumption	I _{VREF}	1.25 V reference	—	67	97	μA
		2.5 V reference	—	55	72	μA
ADC and DAC VREF matching	V _{REF_MATCH}	1.25 V reference	—	99.85	—	%
		2.5 V reference	—	100.01	—	%

Note:

1. Measured with a static input code and no loading on the output. Includes required contribution from the voltage reference.

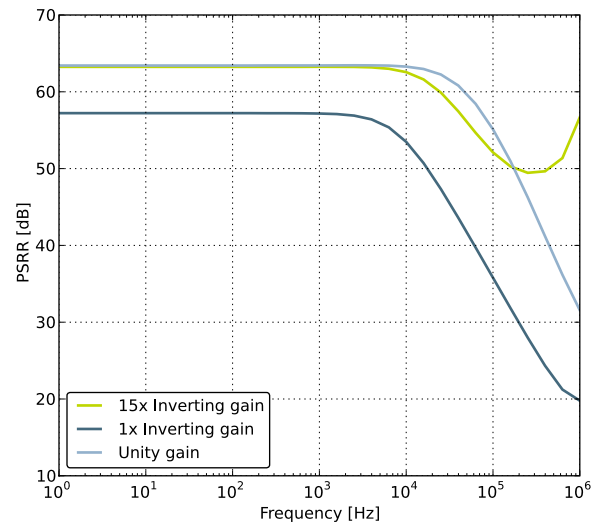


Figure 4.33. OPAMP Negative Power Supply Rejection Ratio

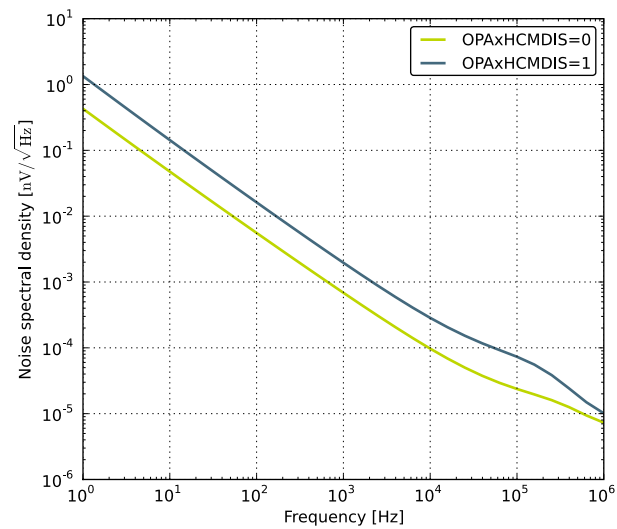


Figure 4.34. OPAMP Voltage Noise Spectral Density(Unity Gain) $V_{out}=1V$

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0	PA0	PA0					External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.

BGA120 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
M11	AVSS_0	Analog ground 0.				
M12	PD3	ADC0_CH3 OPAMP_N2		TIM0_CC2 #3	US1_CS #1	ETM_TD1 #0/2
M13	PD6	ADC0_CH6 OPAMP_P1		TIM1_CC0 #4 LE- TIM0_OUT0 #0 PCNT0_S0IN #3	US1_RX #2 I2C0_SDA #1	LES_ALTEX0 #0 ACMP0_O #2 ETM_TD0 #0
N1	PB8	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	
N2	PC5	ACMP0_CH5 OPAMP_N0	EBI_NANDWEn #0/1/2	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
N3	PA9		EBI_DTEN #0/1/2	TIM2_CC1 #0		
N4	PA11		EBI_HSNC #0/1/2			
N5	PA12		EBI_A00 #0/1/2	TIM2_CC0 #1		
N6	PB11	DAC0_OUT0 / OPAMP_OUT0		TIM1_CC2 #3 LE- TIM0_OUT0 #1	I2C1_SDA #1	
N7	PB12	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
N8	AVSS_2	Analog ground 2.				
N9	PB13	HFXTAL_P			US0_CLK #4/5 LEU0_TX #1	
N10	PB14	HFXTAL_N			US0_CS #4/5 LEU0_RX #1	
N11	AVDD_0	Analog power supply 0.				
N12	PD2	ADC0_CH2	EBI_A27 #0/1/2	TIM0_CC1 #3	US1_CLK #1	DBG_SWO #3
N13	PD5	ADC0_CH5 OPAMP_OUT2 #0			LEU0_RX #0	ETM_TD3 #0/2

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1	PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0	PF6	PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	PC0	PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	PC1	PF2		Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	PC2	PF3		Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14	PC3	PF4		Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	PC4	PF5		Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10	PB0	PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11	PB1	PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2	PB11	PC13			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8					Timer 2 Capture Compare input / output channel 0.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0	PA0	PA0					External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 / OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
LES_CH9	PC9							LESENSE channel 9.
LES_CH10	PC10							LESENSE channel 10.
LES_CH11	PC11							LESENSE channel 11.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN		PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN		PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0							Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1							Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1	PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0	PF6	PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	PC0	PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	PC1	PF2		Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3				PC2			Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4				PC3			Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5		PF5		PC4	PF5		Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0		PE10	PB0	PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1		PE11	PB1	PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2		PE12	PB2	PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8					Timer 2 Capture Compare input / output channel 0.

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
L8	PB13	HFX TAL_P			US0_CLK #4/5 LEU0_TX #1	
L9	PB14	HFX TAL_N			US0_CS #4/5 LEU0_RX #1	
L10	AVDD_0	Analog power supply 0.				
L11	PD0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	

8. CSP81 Package Specifications

8.1 CSP81 Package Dimensions

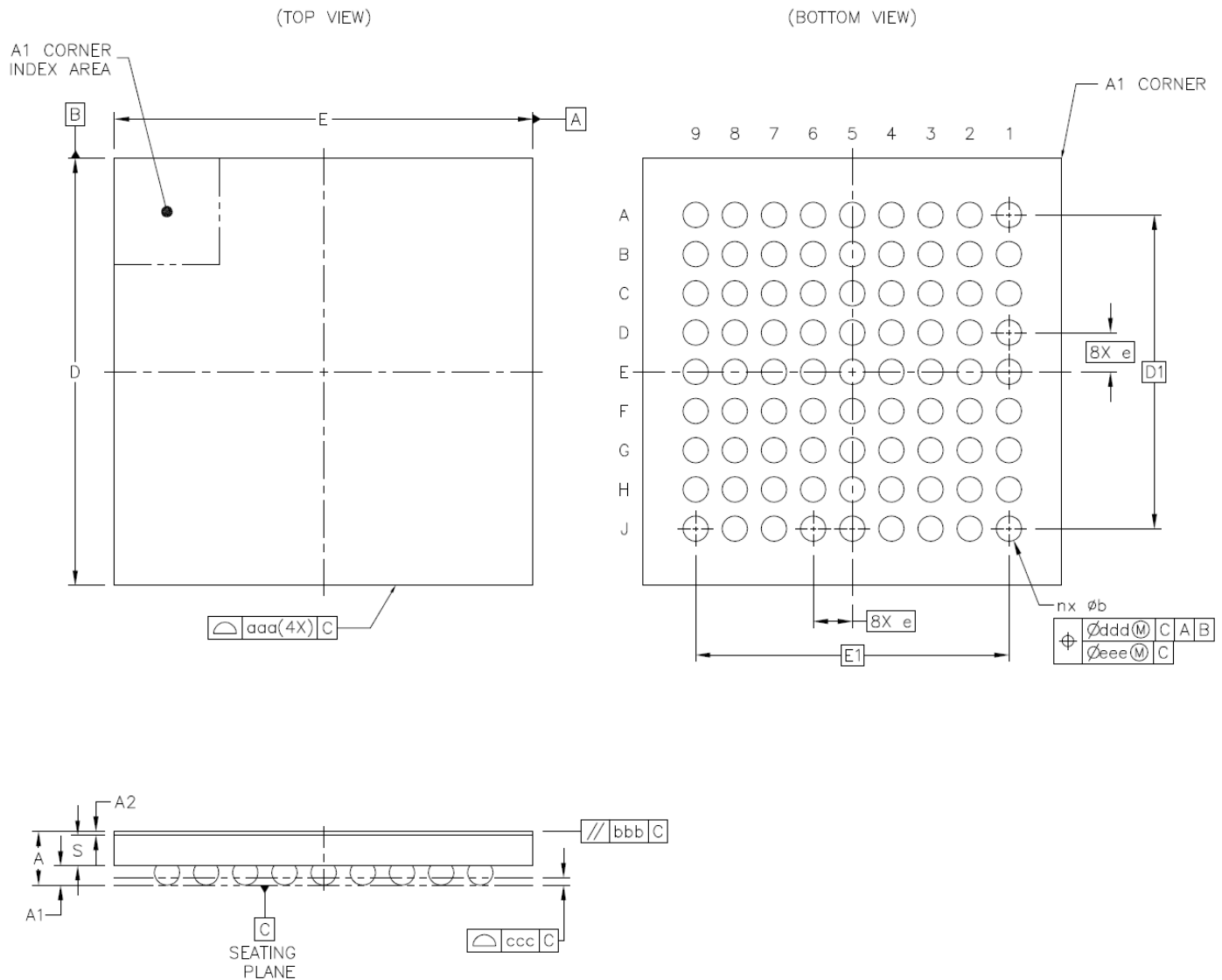


Figure 8.1. CSP81

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Primary datum "C" and seating plane are defined by the spherical crowns of the solder balls.
4. Dimension "b" is measured at the maximum solder bump diameter, parallel to primary datum "C".
5. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

Table 8.1. CSP81 (Dimensions in mm)

Symbol	Min	Nom	Max
A	0.491	0.55	0.609
A1	0.17	—	0.23

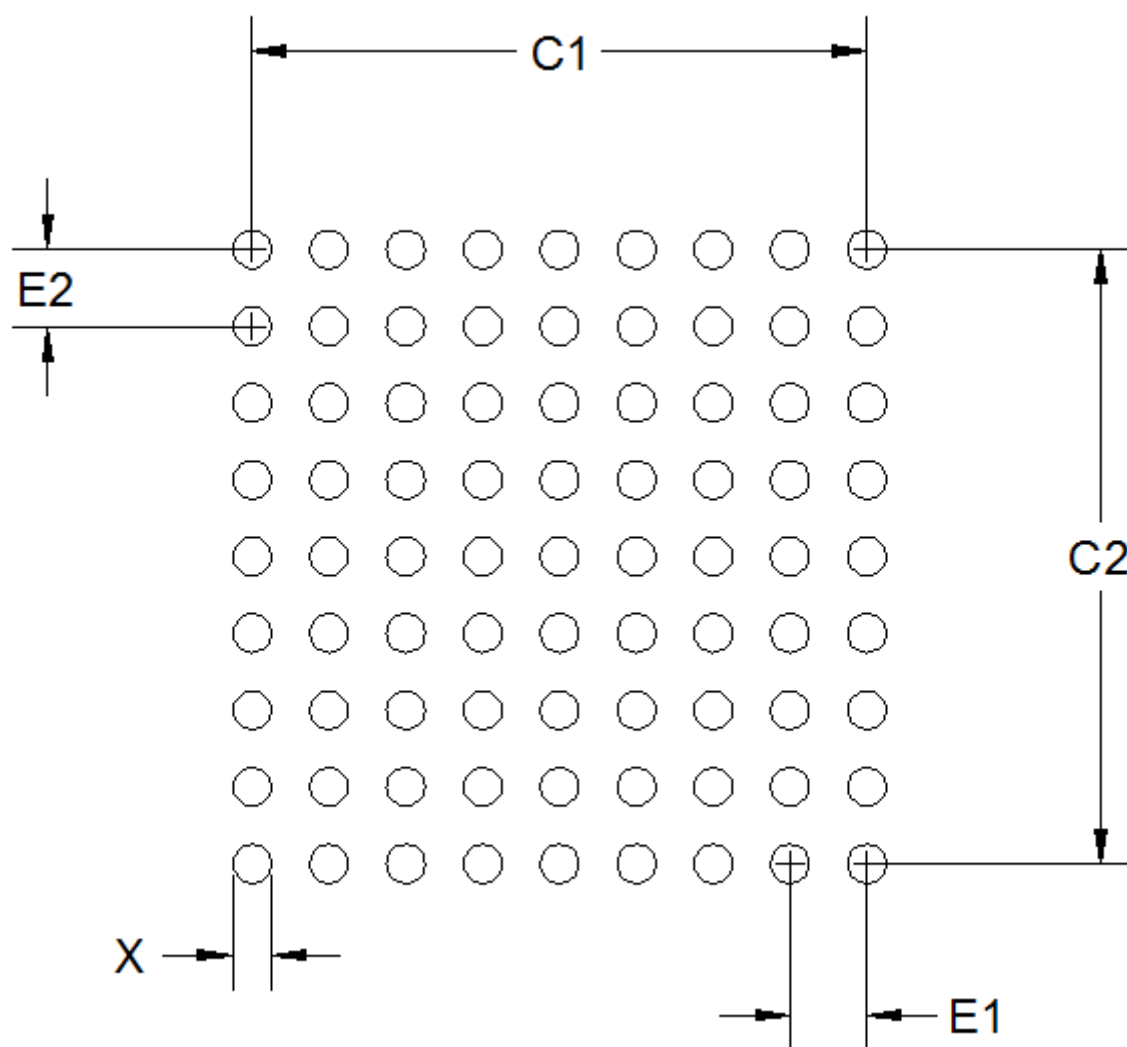


Figure 8.3. CSP81 PCB Solder Mask

Table 8.3. CSP81 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
X	0.26
C1	3.20
C2	3.20
E1	0.40
E2	0.40

- VREF voltage drift (V_{REF_VDRIFT}) – added min, typ, max.
- VREF temperature drift (V_{REF_TDRIFT}) – added min, typ, max.
- VREF current consumption (I_{VREF}) – added typ, max, replacing I_{ADCREF} .
- ADC and DAC VREF matching (V_{REF_MATCH}) – added typical.

4.11 Digital Analog Converter (DAC) – Updated the footnote for active average current (I_{DAC}), and added the following new VREF specs at each voltage reference:

- VREF output voltage (V_{REF}) – added min, typ, max.
- VREF voltage drift (V_{REF_VDRIFT}) – added min, typ, max.
- VREF temperature drift (V_{REF_TDRIFT}) – added min, typ, max.
- VREF current consumption (I_{VREF}) – added typ, max.
- ADC and DAC VREF matching (V_{REF_MATCH}) – added typical.

4.12 Operational Amplifier (OPAMP) – Removed note specifying that OPAMP specs stem from simulations, and added new specifications for the following:

- Active Current (I_{OPAMP}) – new specifications at various (new) bias program settings.
- Gain Bandwidth Product (GBW_{OPAMP}) – new (typ) specifications at new bias program settings and DC bias settings.
- Input Offset Voltage (V_{OFFSET}) – specified min, typ, max for Op Amps (OPA0-1).
- Input Bias Current ($I_{OPAMPBIASIN}$) – new min and max specifications.
- Input Offset Current ($I_{OPAMPOFF-SETIN}$) – new min and max specifications.
- Slew Rate (SR_{OPAMP}) – new specifications at new bias program settings.
- Updated footnote.

4.13 Analog Comparator (ACMP) – Added new specifications for the following:

- Input Bias Current ($I_{ACMPBIASIN}$) – added min and max.
- Input Offset Current ($I_{ACMPOFFSETIN}$) – added min and max.
- Active Current (I_{ACMP}) – added two new condition settings, and footnote.
- Negative Response Time ($t_{RESPONSE_N}$) – added new specifications.
- Positive Response Times ($t_{RESPONSE_P}$) – added new specifications.
- Offset Voltage ($V_{ACMPOFFSET}$) – added specifications at new bias program settings.
- ACMP Hysteresis ($V_{ACMPHYST}$) – added specifications for negative and positive hysteresis at various bias program settings.
- VDD SCALED Input Accuracy ($V_{VDDSCALED}$) – added new specifications (typical).

4.14 Voltage Comparator (VCMP) – Added the following new specifications:

- Negative hysteresis ($V_{VCMPHYST_N}$), replacing VCMP hysteresis.
- Positive hysteresis ($V_{VCMPHYST_P}$), replacing VCMP hysteresis.
- Hysteresis Delta ($V_{VCMPHYST_DELTA}$).
- Negative Response Time ($t_{RESPONSE_N}$).
- Positive Response Time ($t_{RESPONSE_P}$).
- Footnote for active current, I_{VCMP} .

4.18 USART SPI – Corrected parameter descriptions for $t_{CS_DIS_MI}$.

4.19 Digital Peripherals – Added (typical) LE Peripheral Interface Clock Current (I_{LFCLK}) specifications with both the LFXO-LFA and LFXO-LFB clock trees.

Removed MSL information (Moisture Sensitivity Level). Instead, MSL information can be found in the Qual report that is available on the Silicon Labs website.

New formatting throughout.

14.5 Revision 1.20

September 30th, 2013

This revision applies the following devices:

- EFM32LG230
- EFM32LG232
- EFM32LG280
- EFM32LG290
- EFM32LG295
- EFM32LG330
- EFM32LG332
- EFM32LG380
- EFM32LG390
- EFM32LG395
- EFM32LG840
- EFM32LG842
- EFM32LG880
- EFM32LG890
- EFM32LG895
- EFM32LG940
- EFM32LG942
- EFM32LG980
- EFM32LG990
- EFM32LG995

Added I2C characterization data.

Added SPI characterization data.

Corrected the DAC and OPAMP2 pin sharing information in the Alternate Functionality Pinout section.

Corrected GPIO operating voltage from 1.8 V to 1.85 V.

For devices with USB, added the USB bootloader information.

Corrected the ADC resolution from 12, 10 and 6 bit to 12, 8 and 6 bit.

For QFN64 packages, removed UART mentioned incorrectly in the QFN64 parts.

Updated Environmental information.

Updated trademark, disclaimer and contact information.

Other minor corrections.

This revision applies the following devices:

- EFM32LG900

March 16th, 2015

Corrected pad numbers and the order of the pads in the padout table so that it matches the drawing.